

CLAIMS

1. A transfer molding apparatus comprises:

5 a top-half mold and a bottom-half mold for forming a cavity as a molding space for a package and a transfer pot as a loading space, communicating with said cavity, for resin to be injected into said cavity;

a plunger for forcing the resin out of the transfer pot into said cavity;
and

10 pressure adjusting means for reducing the pressure in said cavity when a specified amount of resin has been injected into said cavity.

2. A transfer molding apparatus according to Claim 1, wherein said top-half mold and said bottom-half mold form a plurality of cavities interconnected, and wherein said pressure adjusting means reduces the pressure of the cavities every time a specified amount of resin is supplied into any one of a
15 plurality of cavities.

3. A transfer molding apparatus according to Claim 1, wherein said pressure adjusting means includes position detecting means for detecting the position of said plunger when a specified amount of resin has been supplied into said cavity.

20 4. A transfer molding apparatus according to Claim 2, wherein said pressure adjusting means includes position detecting means for detecting the position of said plunger when a specified amount of resin has been supplied into said cavity.

5. A transfer molding apparatus according to Claim 1, wherein said
25 pressure adjusting means includes time counting means for counting time from the start of movement of said plunger until a specified amount of said resin has been supplied into said cavity.

6. A transfer molding apparatus according to Claim 2, wherein said pressure adjusting means includes time counting means for counting time from the start of movement of said plunger until a specified amount of said resin has been supplied into said cavity.
- 5 7. A method for manufacturing semiconductor devices comprising the steps of:
 - placing a semiconductor-element-mounted lead frame between a top-half mold and a bottom-half mold; and
 - reducing the pressure in a cavity formed by said top-half mold and said
- 10 bottom-half mold when a specified amount of resin has been supplied into said cavity.